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Attorney Docket: 501010.20522  
Today's Date: October 25, 2002  
Serial No. 10/045,651  
Filing Date: November 7, 2001  
For: MULTI-LAYER PRINTED CIRCUIT BOARD FABRICATION  
SYSTEM AND METHOD

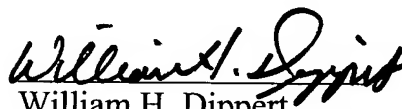
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FIRST CLASS MAILING CERTIFICATE

FIRST CLASS MAIL

**Deposited: October 25, 2002**

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail under 37 CFR 1.10 on the date indicated above and is addressed to: Commissioner for Patents, Washington, D.C. 20231.

  
William H. Dippert  
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TC 2800 MAIL ROOM

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